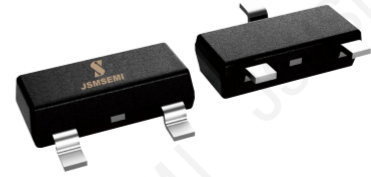
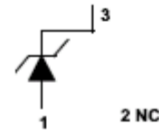


FEATURES

- ◆ Planar Die Construction.
- ◆ 350mw Power Dissipation.
- ◆ Zener Voltages From 2.4V -51V
- ◆ Ideally Suited For Automated Assembly Processes



CONNECTION
DIAGRAM



APPLICATIONS

- ◆ 350Mw Surface mount zener diode

MAXIMUM RATING @ Ta=25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Forward Voltage@I _F =10mA	V _F	0.9	V
Power Dissipation	P _d	350	mW
Thermal Resistance, Junction to Ambient Air	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{stg}	-65 to+150	°C

- Notes: 1. Valid provided that device terminals are kept at ambient temperature.
 2. Tested with pulses, 300µs pulse width, period = 5ms.
 3. f = 1KHz.

ELECTRICAL CHARACTERISTICS@ Ta=25°C unless otherwise specified

Type Number	Marking Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current		Typical Temperature Coefficient @I _{ZT} mV/°C	
		V _Z @I _{ZT}			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}		I _R	V _R	Min	Max
		Nom(V)	Min(V)	Max(V)	(mA)	(Ω)	(Ω)	(mA)	(µA)	(V)		
BZX84-C18,215-JSM	Y6	18	16.8	19.1	5.0	45	225	1.0	0.1	12.6	12.4	16.0

TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

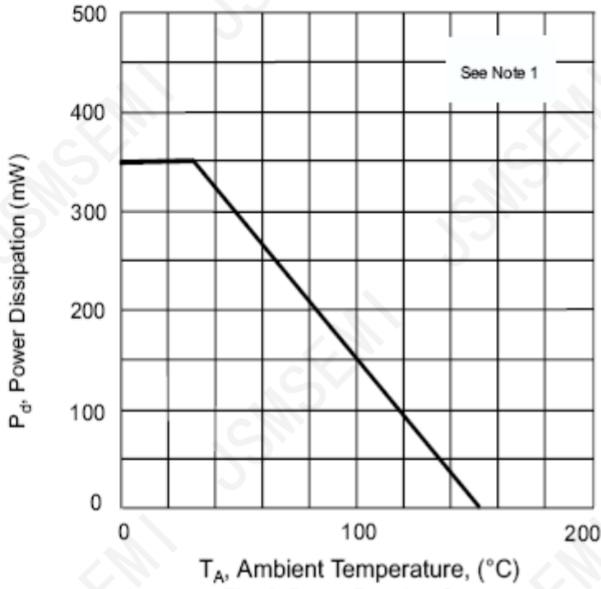


Fig. 1 Power Derating Curve

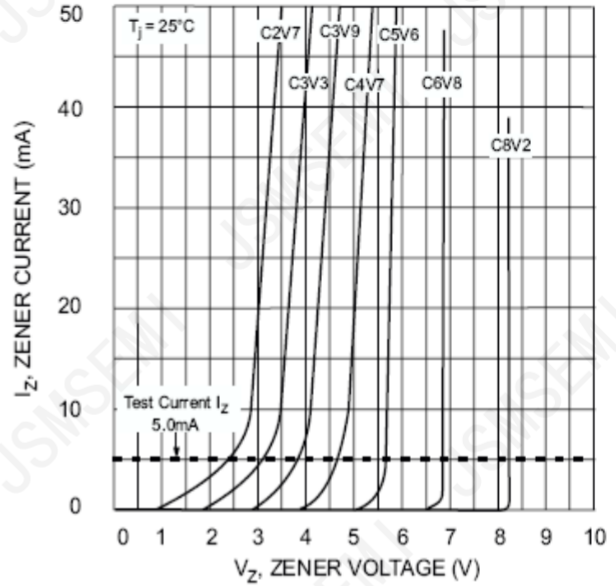


Fig. 2 Zener Breakdown Characteristics

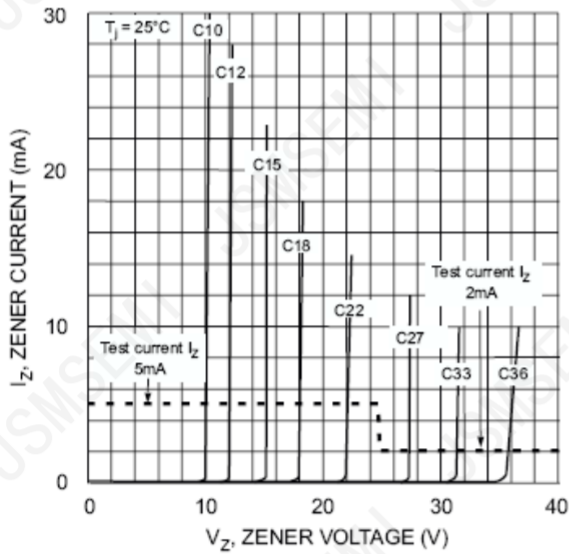


Fig. 3 Zener Breakdown Characteristics

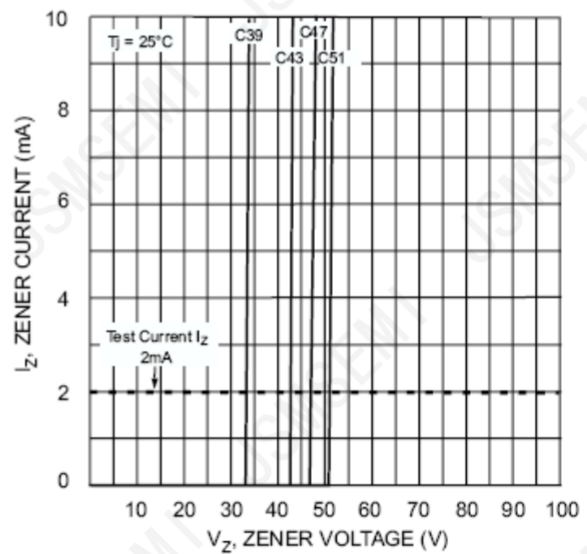
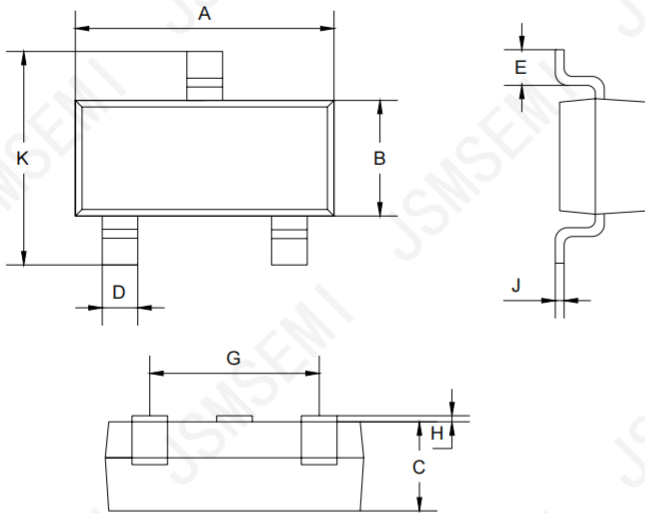


Fig. 4 Zener Breakdown Characteristics

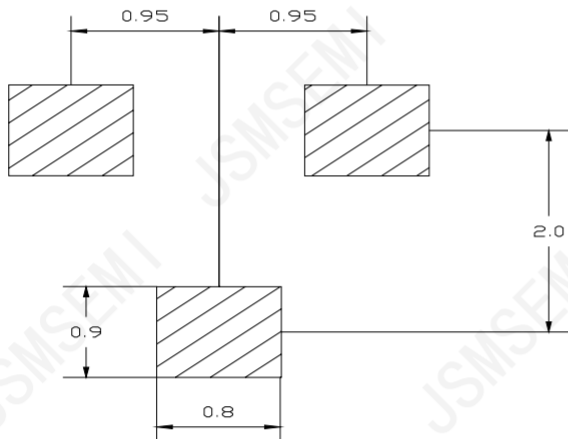
PACKAGE OUTLINE

Plastic surface mounted package

SOT-23



SOT-23		
Dim	Min	Max
A	2.85	2.95
B	1.25	1.35
C	1.0Typical	
D	0.37	0.43
E	0.35	0.48
G	1.85	1.95
H	0.02	0.1
J	0.1Typical	
K	2.35	2.45
All Dimensions in mm		

SOLDERING FOOTPRINT


Unit : mm

PACKAGE INFORMATION

Device	Package	Shipping
BZX84-C18,215-JSM	SOT-23	3000/Tape&Reel

Revision History

Rev.	Change	Date
V1.0	Initial version	2/23/2024

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